

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

Applicant: **Vierk et al.**

Case: **A-66435/JAS/MSS**

Serial No.: **09/314,262**

Filed: **May 18, 1999**

Group Art Unit: **1773**

Examiner: **S. Resan**

Title: **HIGH MODULUS AND HIGH DAMPING PLASTIC COMPOSITE DISC
SUBSTRATE FOR IMPROVED SERVO CONTROL BY INJECTION AND
CO-INJECTION MOLDING**

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D. C. 20231

S I R:

PRELIMINARY AMENDMENT

In response to the Office Action dated September 13, 2001, please amend
the above-identified patent application as follows:

IN THE CLAIMS

Please rewrite claims 1, 5, 14, 17 and 19.

*Sub
P1*
(Twice Amended) A substrate for use in a data storage system,
comprising:

at least one plastic composite material exhibiting a modulus of about
350 kpsi or greater;

*AET
#10/B
2/26/02*

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